

MOSFET - Power, Single N-Channel, SUPERFET[®] V, FAST, TO220

600 V, 185 mΩ, 15 A

NTP185N60S5H

Description

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application.

Features

- 650 V @ T_J = 150°C
- Typ. R_{DS(on)} = 148 mΩ
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

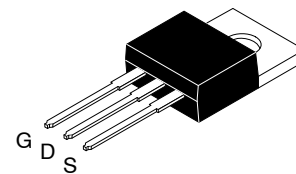
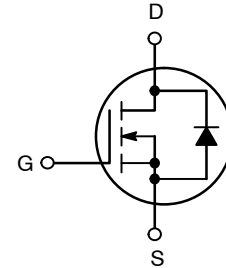
ABSOLUTE MAXIMUM RATINGS (T_J = 25°C, Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	600	V
Gate-to-Source Voltage	V _{GSS}	DC	±30
		AC (f > 1 Hz)	±30
Continuous Drain Current	I _D	T _C = 25°C	15
		T _C = 100°C	9
Power Dissipation	P _D	116	W
Pulsed Drain Current (Note 1)	I _{DM}	53	A
Pulsed Source Current (Body Diode) (Note 1)	I _{SM}	53	A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C
Source Current (Body Diode)	I _S	15	A
Single Pulse Avalanche Energy	I _L = 3.6 A, R _G = 25 Ω	E _{AS}	124
Avalanche Current	I _{AS}	3.6	A
Repetitive Avalanche Energy (Note 1)	E _{AR}	1.16	mJ
MOSFET dv/dt	dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)		20	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)	T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

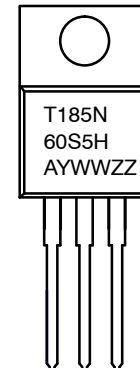
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{SD} ≤ 7.5 A, di/dt ≤ 200 A/μs, V_{DD} ≤ 400 V, starting T_J = 25°C.

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
600 V	185 mΩ @ 10 V	15 A



TO-220-3LD
CASE 340AT

MARKING DIAGRAM



T185N60S5H = Specific Device Code
A = Assembly Plant Code
YWW = Date Code (Year & Week)
ZZ = Lot

ORDERING INFORMATION

Device	Package	Shipping
NTP185N60S5H	TO220	50 Units / Tube

NTP185N60S5H

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{\theta JC}$	1.08	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{\theta JA}$	62.5	

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
-----------	-----------------	--------	-----	-----	-----	------

OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$	$V_{(BR)DSS}$	600	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, Referenced to 25°C	$\Delta V_{(BR)DSS} / \Delta T_J$	-	630	-	mV/°C
Zero Gate Voltage Drain Current	$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}, T_J = 25^\circ\text{C}$	I_{DSS}	-	-	1	μA
Gate-to-Source Leakage Current	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	I_{GSS}	-	-	±100	nA

ON CHARACTERISTICS

Drain-to-Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 7.5\text{ A}, T_J = 25^\circ\text{C}$	$R_{DS(on)}$	-	148	185	mΩ
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1.4\text{ mA}, T_J = 25^\circ\text{C}$	$V_{GS(th)}$	2.7	-	4.3	V
Forward Trans-conductance	$V_{DS} = 20\text{ V}, I_D = 7.5\text{ A}$	g_{FS}	-	18	-	S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, f = 250\text{ kHz}$	C_{ISS}	-	1350	-	pF
Output Capacitance		C_{OSS}	-	25	-	
Time Related Output Capacitance	$I_D = \text{Constant}, V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	$C_{OSS(tr)}$	-	372	-	
Energy Related Output Capacitance		$C_{OSS(er)}$	-	42	-	
Total Gate Charge	$V_{DD} = 400\text{ V}, I_D = 7.5\text{ A}, V_{GS} = 10\text{ V}$	$Q_{G(tot)}$	-	25	-	nC
Gate-to-Source Charge		Q_{GS}	-	7	-	
Gate-to-Drain Charge		Q_{GD}	-	8	-	
Gate Resistance	$f = 1\text{ MHz}$	R_G	-	0.9	-	Ω

SWITCHING CHARACTERISTICS

Turn-On Delay Time	$V_{GS} = 0/10\text{ V}, V_{DD} = 400\text{ V}, I_D = 7.5\text{ A}, R_G = 10\text{ }\Omega$	$t_{d(on)}$	-	18	-	ns
Rise Time		t_r	-	9	-	
Turn-Off Delay Time		$t_{d(off)}$	-	53	-	
Fall Time		t_f	-	4	-	

SOURCE-TO-DRAIN DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 7.5\text{ A}, T_J = 25^\circ\text{C}$	V_{SD}	-	-	1.2	V
Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 7.5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, V_{DD} = 400\text{ V}$	t_{RR}	-	251	-	ns
Reverse Recovery Charge		Q_{RR}	-	3028	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NTP185N60S5H

TYPICAL CHARACTERISTICS

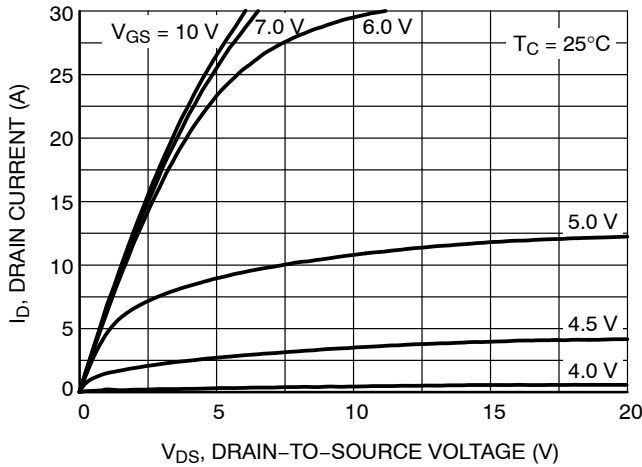


Figure 1. On-Region Characteristics

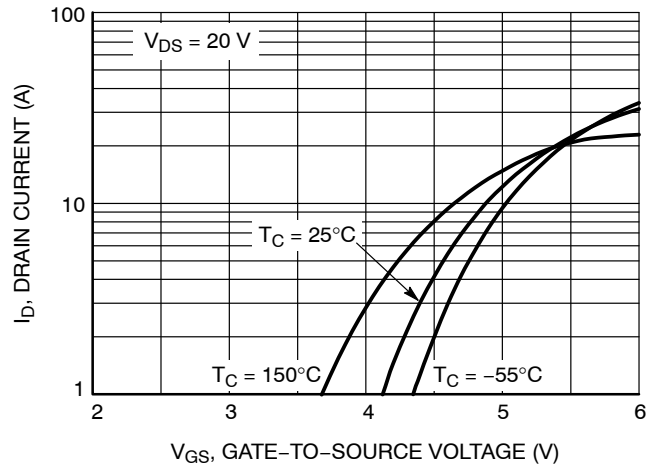


Figure 2. Transfer Characteristics

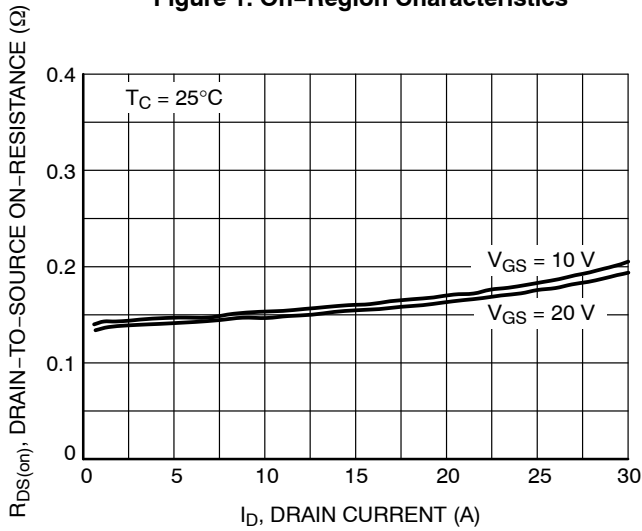


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

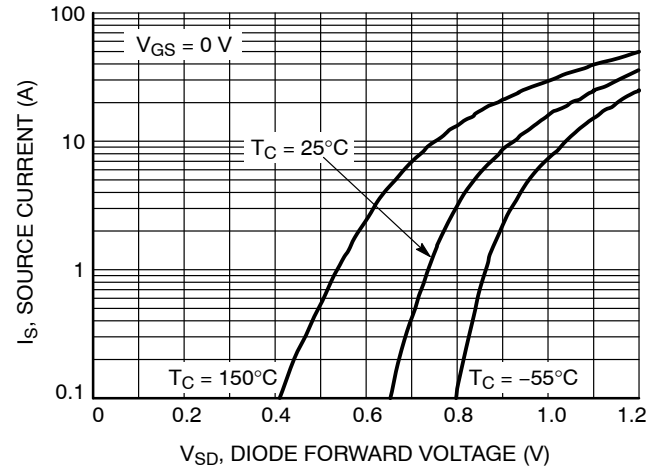


Figure 4. Diode Forward Voltage vs. Source Current

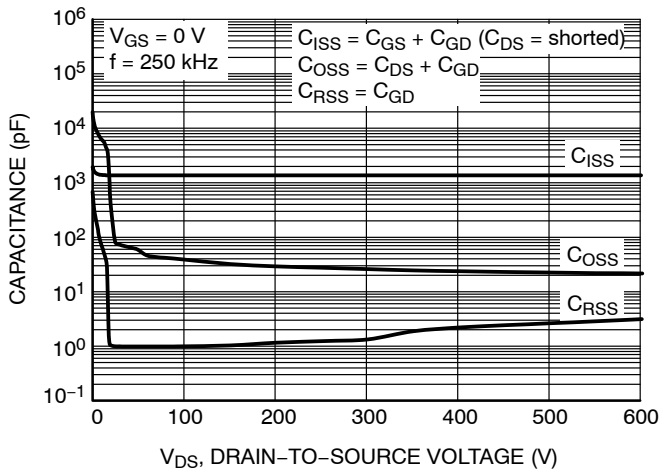


Figure 5. Capacitance Characteristics

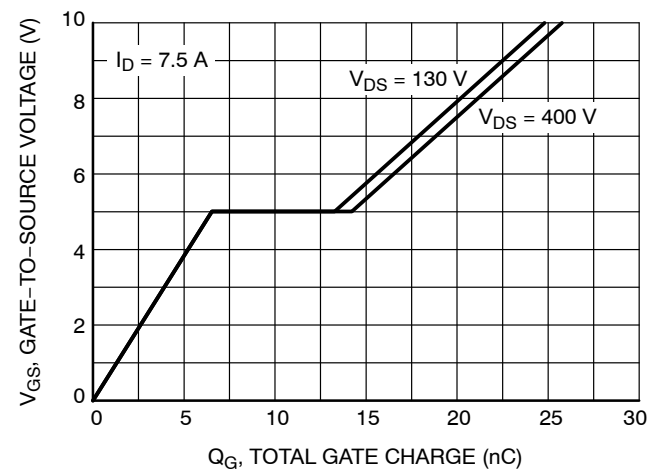


Figure 6. Gate Charge Characteristics

NTP185N60S5H

TYPICAL CHARACTERISTICS

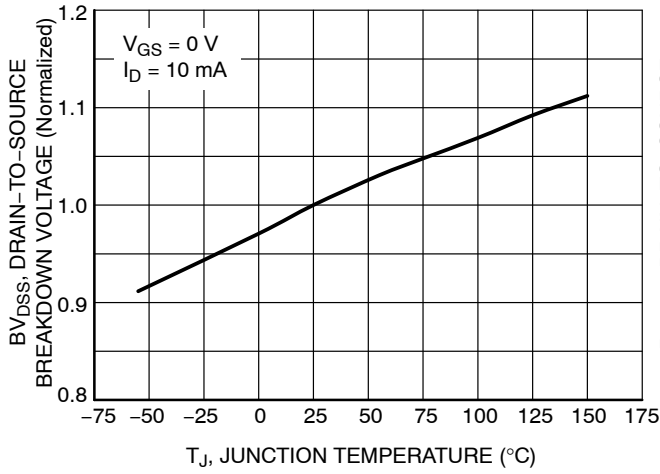


Figure 7. Breakdown Voltage Variation vs. Temperature

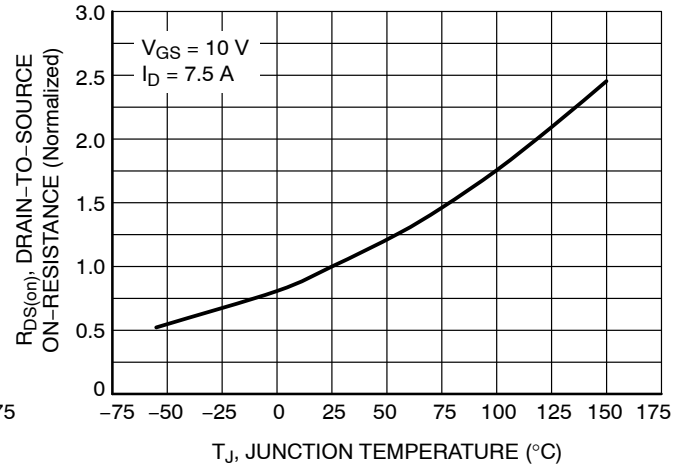


Figure 8. On-Resistance Variation vs. Temperature

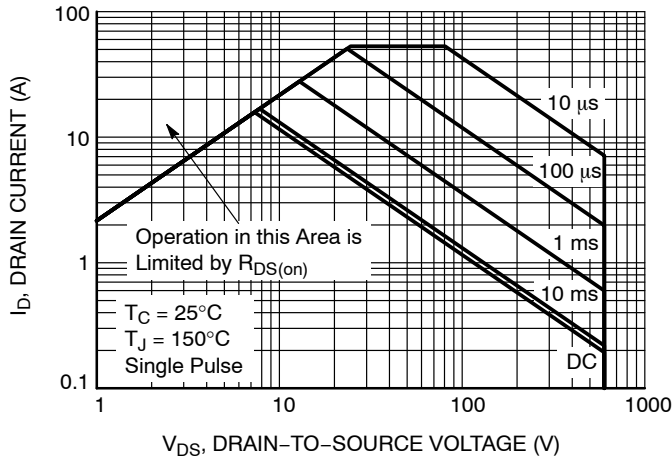


Figure 9. Maximum Safe Operating Area

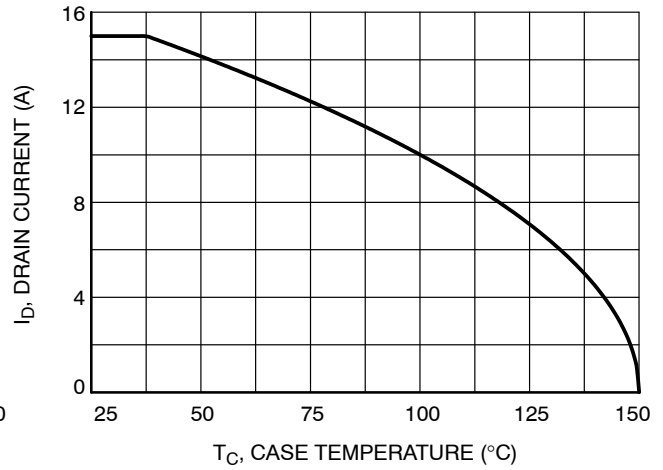


Figure 10. Maximum Drain Current vs. Case Temperature

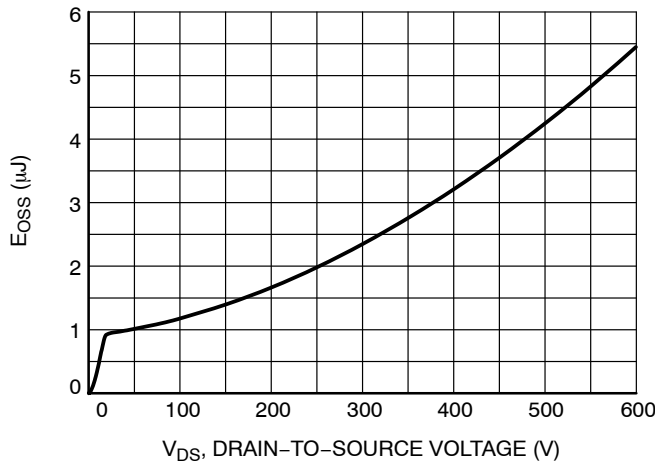


Figure 11. E_{OSS} vs. Drain-to-Source Voltage

NTP185N60S5H

TYPICAL CHARACTERISTICS

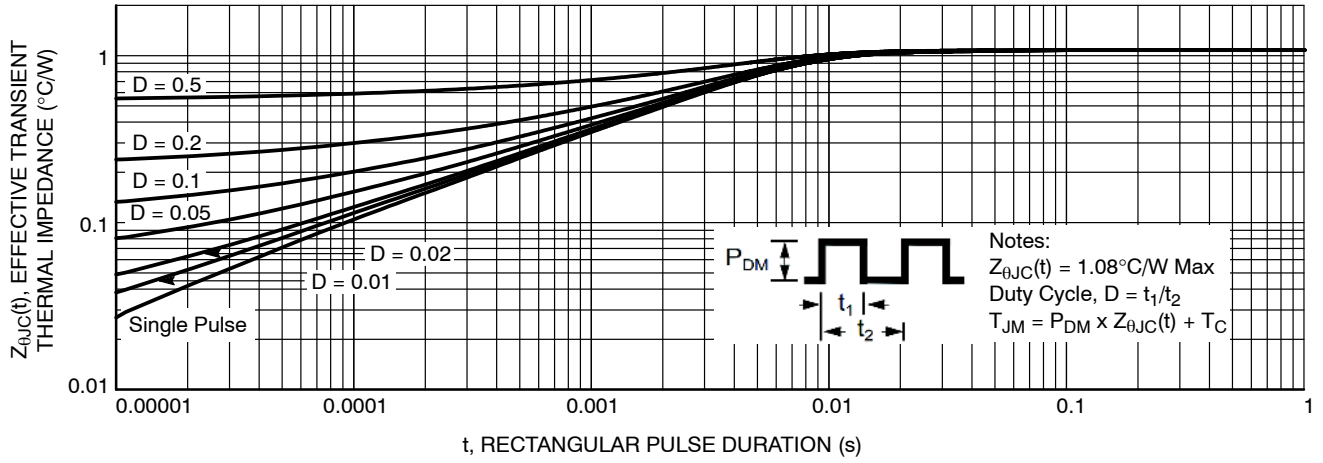


Figure 12. Transient Thermal Impedance

NTP185N60S5H

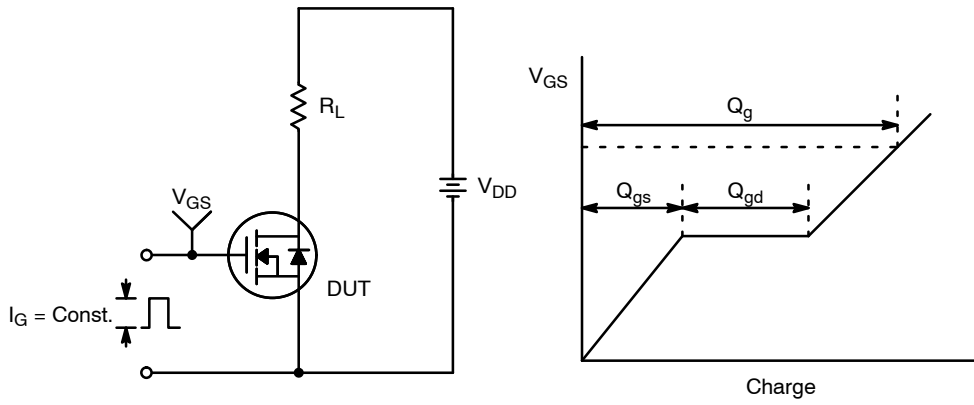


Figure 13. Gate Charge Test Circuit & Waveform

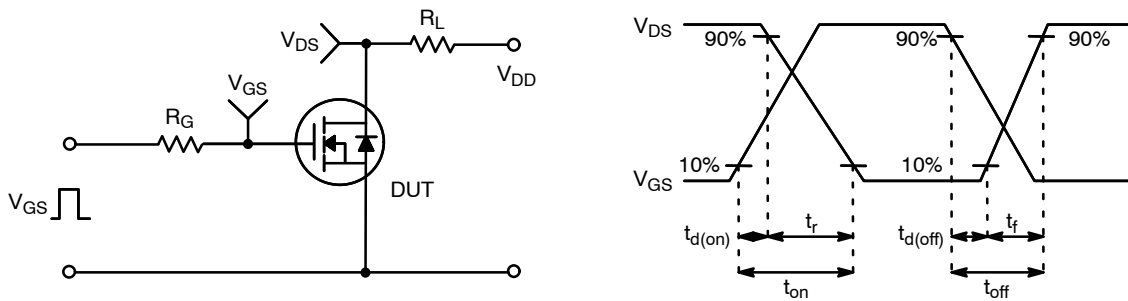


Figure 14. Resistive Switching Test Circuit & Waveforms

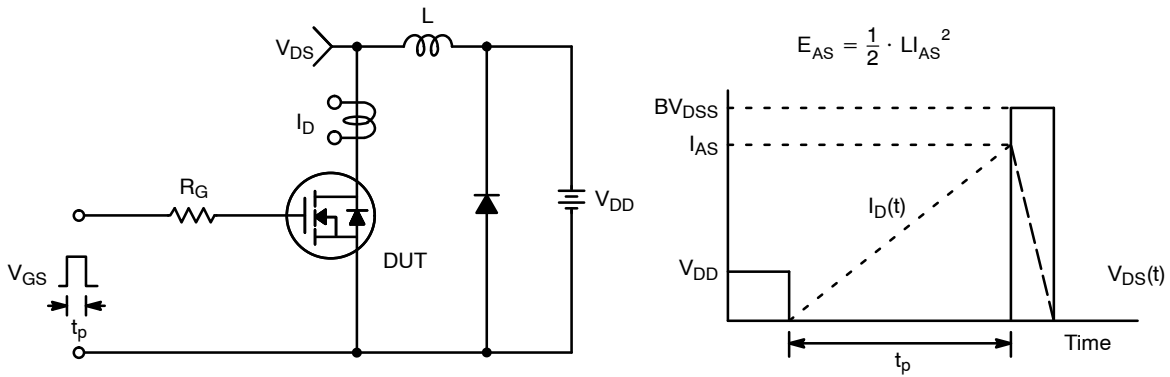


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

NTP185N60S5H

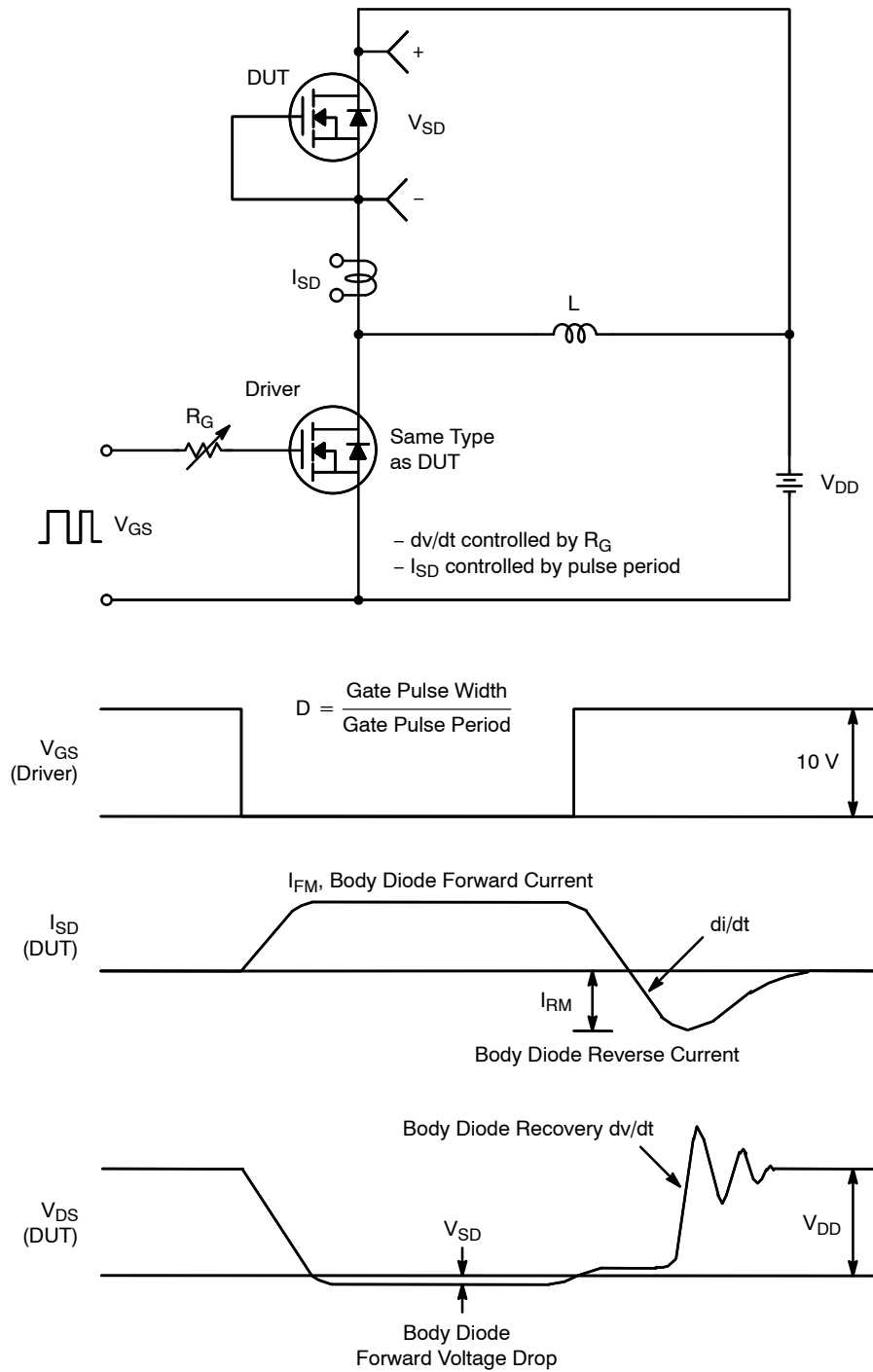
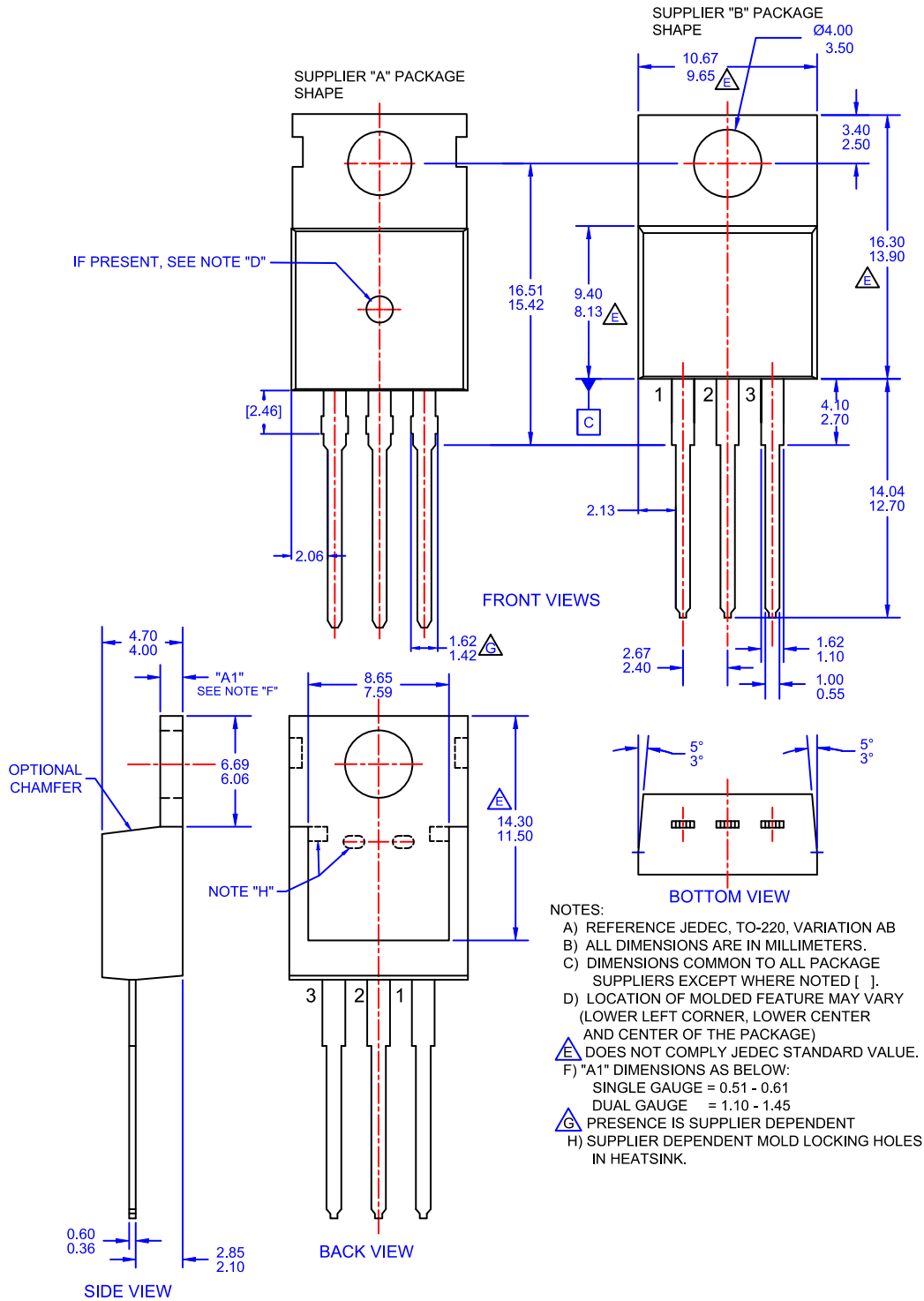


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

NTP185N60S5H

PACKAGE DIMENSIONS

TO-220-3LD
CASE 340AT
ISSUE A



- NOTES:
- A) REFERENCE JEDEC, TO-220, VARIATION AB
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS COMMON TO ALL PACKAGE SUPPLIERS EXCEPT WHERE NOTED [].
 - D) LOCATION OF MOLDED FEATURE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE)
 - E) DOES NOT COMPLY JEDEC STANDARD VALUE.
 - F) "A1" DIMENSIONS AS BELOW:
SINGLE GAUGE = 0.51 - 0.61
DUAL GAUGE = 1.10 - 1.45
 - G) PRESENCE IS SUPPLIER DEPENDENT
 - H) SUPPLIER DEPENDENT MOLD LOCKING HOLES IN HEATSINK.

NTP185N60S5H

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT
North American Technical Support:
Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:
Phone: 00421 33 790 2910
For additional information, please contact your local Sales Representative